

# HCB120S10D1

## SiC Silicon Carbide Schottky Diode

1200V, 10A

### Description

The 1200V SiC is an advanced Power Master Semiconductor's silicon carbide diode family. This technology combines the benefits of excellent low forward voltage and robustness. Consequently, the SiC family is suitable for application requiring high power efficiency.

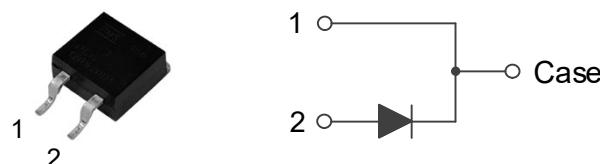
### Applications

- Solar inverter, UPS
- EV charging station
- Power Factor Correction

### Features

$V_{RRM}$	$I_F$	$T_{J,max}$	$Q_C$
1200 V	10 A	175 °C	63 nC

- No reverse recovery current
- Low forward voltage
- 175°C Max junction temperature
- High surge current capability
- Switching behavior independent of temperature
- Pb-Free, Halogen Free and RoHS compliant



### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage		1200	V
$I_F$	Forward Current	$T_C=154^\circ\text{C}$	10	A
$I_{F,SM}$	Non-Repetitive Forward Surge Current	$T_C=25^\circ\text{C}, t_p=10\text{ms}$	79	A
		$T_C=150^\circ\text{C}, t_p=10\text{ms}$	67	A
$I_{F,Max}$	Non-Repetitive Peak Forward Current	$T_C=25^\circ\text{C}, t_p=10\mu\text{s}$	810	A
		$T_C=150^\circ\text{C}, t_p=10\mu\text{s}$	690	A
$I^2dt$ value	$\int I^2t$	$T_C=25^\circ\text{C}, t_p=10\text{ms}$	31	$\text{A}^2\text{s}$
		$T_C=150^\circ\text{C}, t_p=10\text{ms}$	23	$\text{A}^2\text{s}$
$P_{tot}$	Power Dissipation	$T_C=25^\circ\text{C}$	167	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature		-55 to +175	°C

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.9	°C/W

## Package Marking and Ordering Information

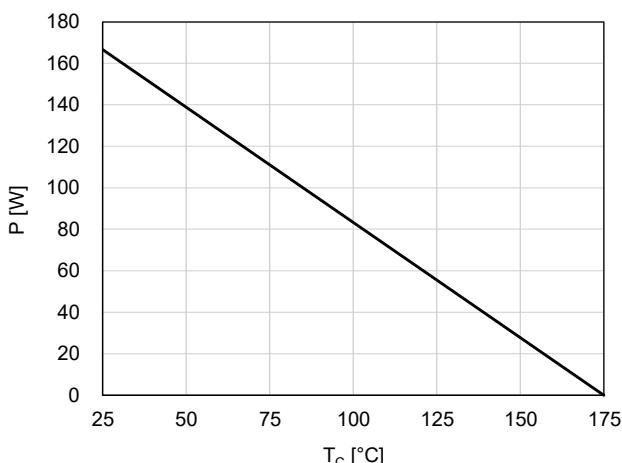
Part Number	Top Marking	Package	Packing Method	Quantity
HCB120S10D1	HCB120S10D1	TO-263	Tape & Reel	2500 units

## Electrical Characteristics ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

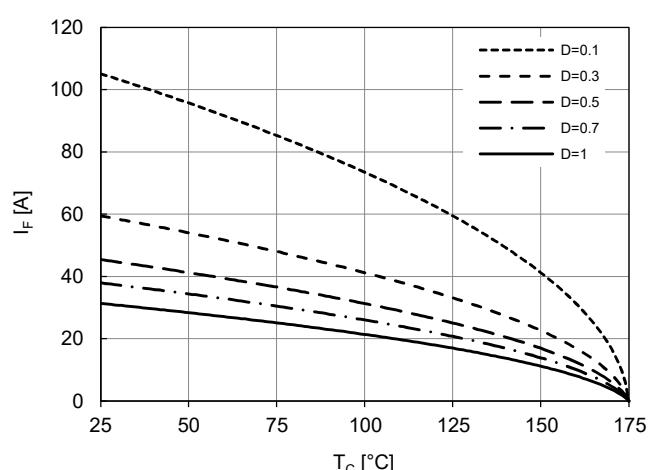
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_F$	Forward Voltage	$I_F=10\text{A}, T_C=25^\circ\text{C}$		1.39	1.70	V
		$I_F=10\text{A}, T_C=175^\circ\text{C}$		1.8	-	
$I_R$	Reverse Current	$V_R=1200\text{V}, T_C=25^\circ\text{C}$		-	100	$\mu\text{A}$
		$V_R=1200\text{V}, T_C=175^\circ\text{C}$		-	300	
$Q_C$	Total Capacitive Charge	$V_R=800\text{V}, T_C=25^\circ\text{C}$		63		nC
$C$	Total Capacitance	$V_R=1\text{V}, f=100\text{Khz}$		696		pF
		$V_R=800\text{V}, f=100\text{Khz}$		44		
$E_C$	Capacitance Stored Energy	$V_R=800\text{V}, T_C=25^\circ\text{C}$		18		$\mu\text{J}$

### Typical Performance Characteristics

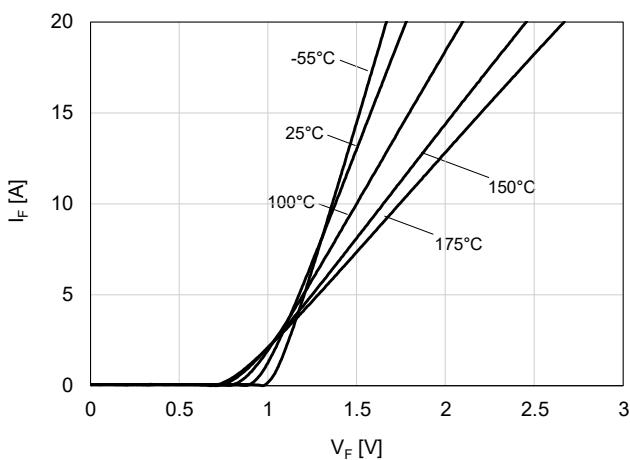
**Figure 1. Power Derating**



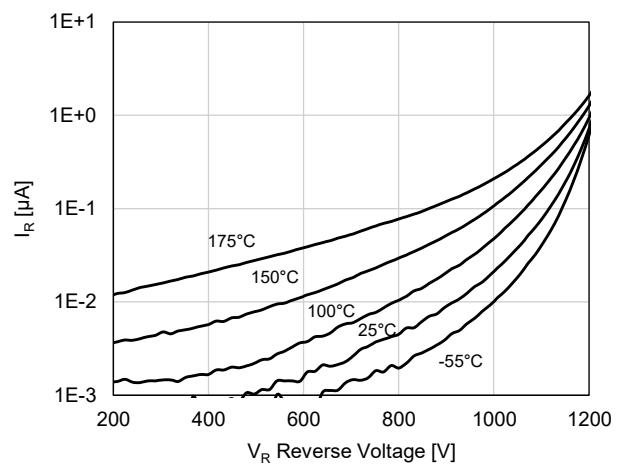
**Figure 2. Current Derating**



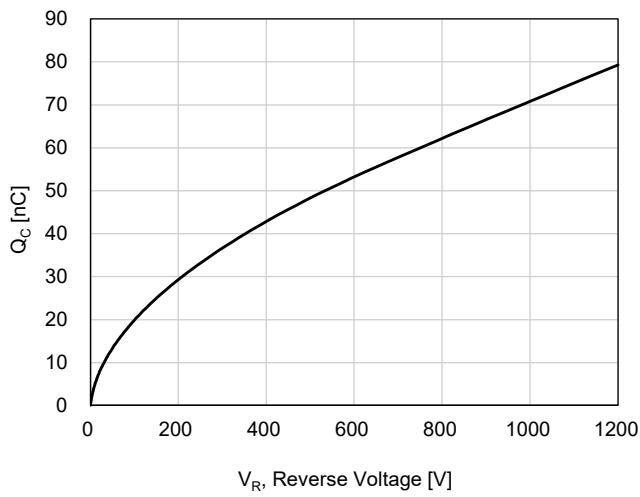
**Figure 3. Forward Characteristics**



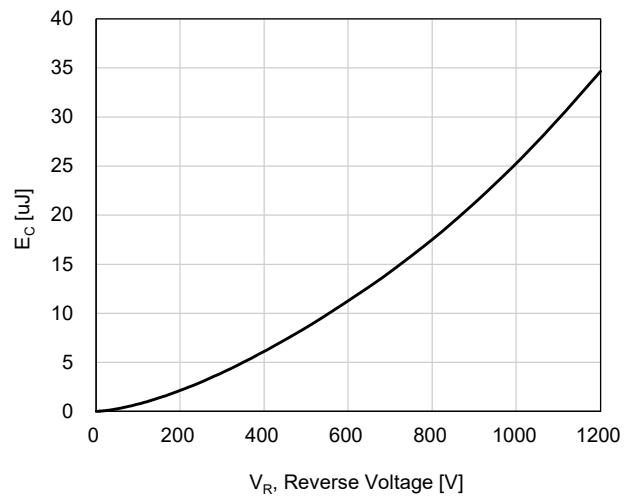
**Figure 4. Reverse Characteristics**

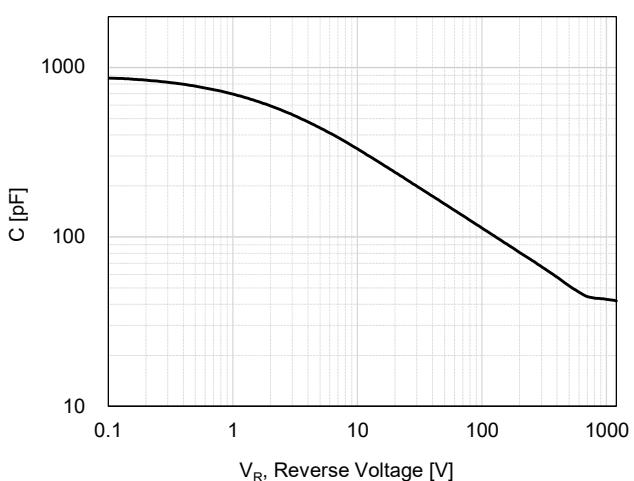
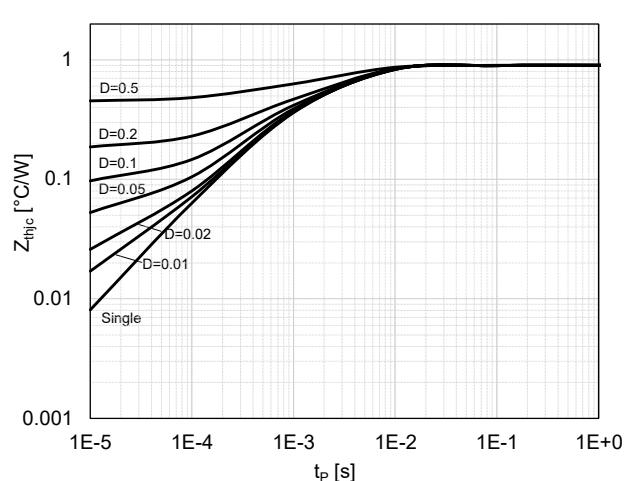


**Figure 5. Capacitive Charge Characteristic**



**Figure 6. Capacitance Stored Energy**

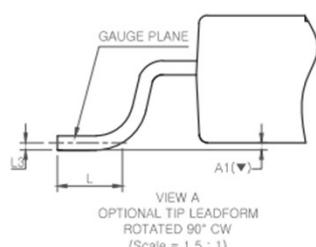
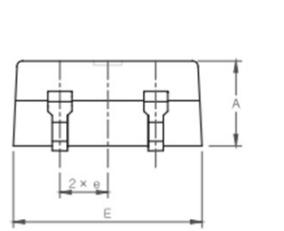
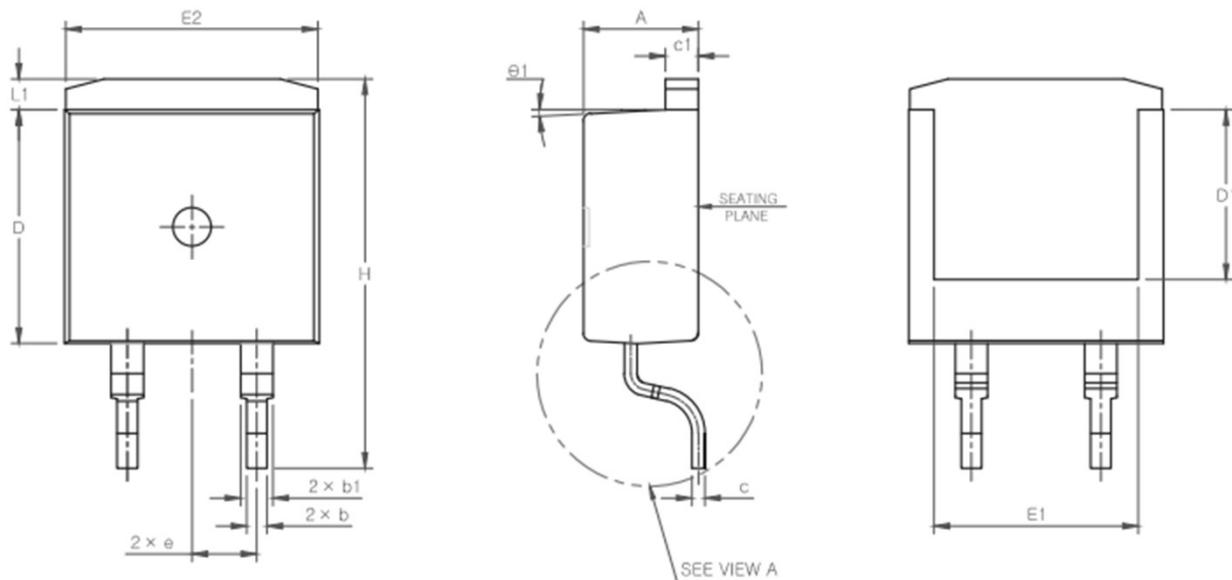


**Typical Performance Characteristics****Figure 7. Capacitance Characteristic****Figure 8. Transient Thermal Response Curve**

## Package Outlines

## TO-263-2L

\* TO-263-2L NC



## NOTE

1. THESE DIMENSIONS DO NOT INCLUDE PROTRUSIONS OF THE MOLD.
2. THE "( )" MARK IS THE REFERENCE
3. COPLANARITY : MAX 0.10mm

SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
A1(▼)	0.00	—	0.25
b	0.70	0.80	0.90
b1	1.17	1.27	1.37
c	0.45	0.50	0.60
c1	1.25	1.30	1.40
D	9.00	9.20	9.40
D1	6.50	6.70	6.90
E	9.80	10.00	10.20
E1	7.80	8.00	8.20
E2	9.70	9.90	10.10
e	2.54 BSC		
H	15.00	15.30	15.60
L	2.00	2.30	2.60
L1	1.00	1.20	1.40
L3	0.254 BSC		
theta1	(3°)		

\* Dimensions in millimeters